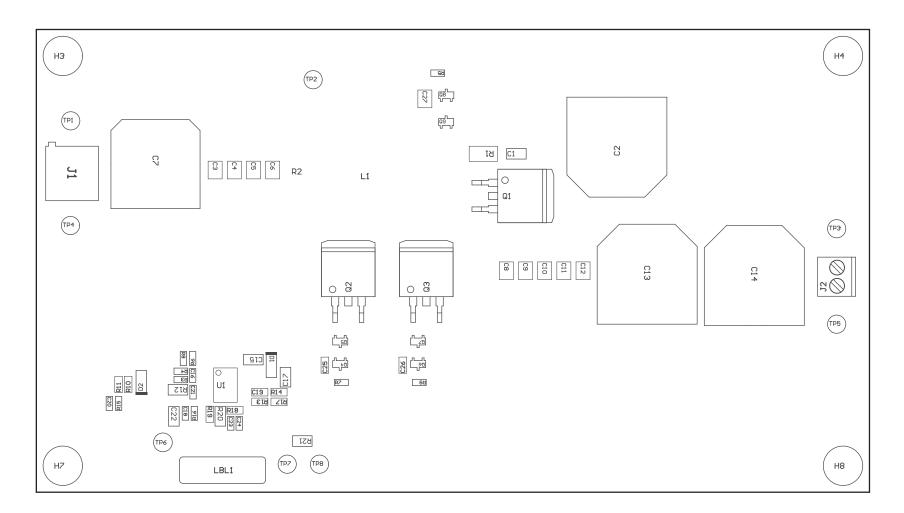
TABLE 1			
Variant	Label text		
001			

ZZ1 ■Install label in silkscreened box after final wash. Text shall be 8 pt font. Text shall be per Table 1

ZZ2 ■ These assemblies are ESD sensitive, ESD precautions shall be observed.

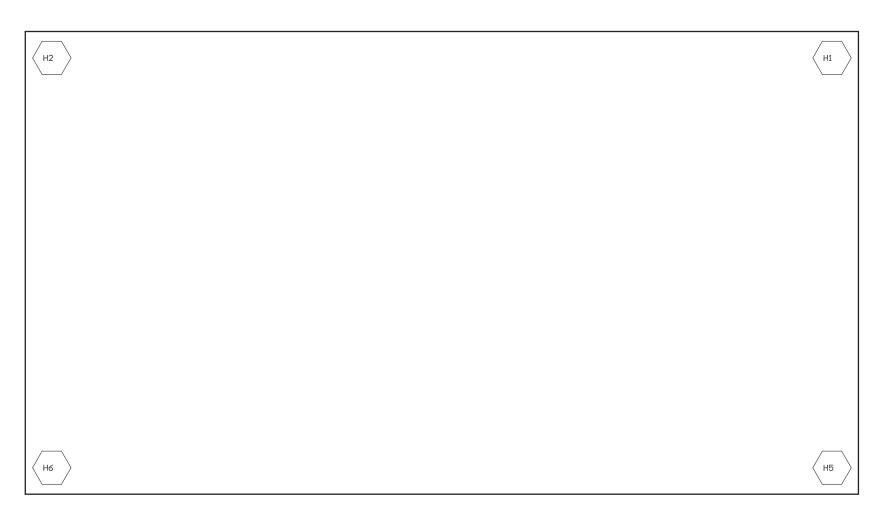
ZZ3 These assemblies must be clean and free from flux and all contaminants. Use of no clean flux is not acceptable.

ZZ4 ■These assemblies must comply with workmanship standards IPC-A-610 Class 2., unless otherwise specified.



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM TOP SIDE	BOARD #: PMP7950 rev1B REV: B	SVN REV: Not In VersionControl
IGNORE ->		
PLOT NAME = Top Assembly Drawing	GENERATED : 4/16/2015 4:20:34	PM TEXAS INSTRUMENTS



COMPONENTS MARKED 'DNP' SHOULD NOT BE POPULATED. ASSEMBLY VARIANT: [No Variations]

PCB VIEWED FROM BOTTOM SIDE	BOARD #: PMP7950 rev1B REV: B	SVN REV: Not In VersionControl	
	IGNORE ->		
PLOT NAME = Bottom Assembly Drawing	GENERATED : 4/16/2015 4:20:35	PM TEXAS INSTRUMENTS	

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